

MEMORY MODULE AND ITS MANUFACTURE

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Abstract

PROBLEM TO BE SOLVED: To realize increase in high density and large capacity.

SOLUTION: This memory module has a module board 2 mounted with a TSOP 1, and this is provided with a male connector 3a on the surface 2a of the module board 2 and is also provided with a female connector 3b electrically connected to this male connector 3a, on the rear surface 2b of the module board 2, whereby a plurality of module boards 2 can be stacked and mounted by connecting the female connectors 3 provided on the rear surface 2b with the male connectors 3a attached to a motherboard 5.

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